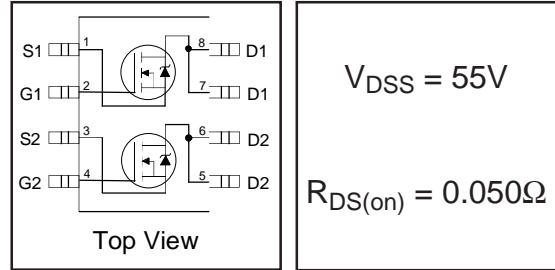


IRF7341IPbF

HEXFET® Power MOSFET

- Generation V Technology
- Ultra Low On-Resistance
- Dual N-Channel Mosfet
- Surface Mount
- Available in Tape & Reel
- Dynamic dv/dt Rating
- Fast Switching
- Lead-Free

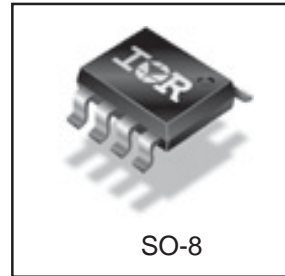


| |
|----------------------------|
| $V_{DS} = 55V$ |
| $R_{DS(on)} = 0.050\Omega$ |

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics and multiple-die capability making it ideal in a variety of power applications. With these improvements, multiple devices can be used in an application with dramatically reduced board space. The package is designed for vapor phase, infra red, or wave soldering techniques. Power dissipation of greater than 0.8W is possible in a typical PCB mount application.



Absolute Maximum Ratings

| | Parameter | Max. | Units |
|--------------------------|---|--------------|-------|
| V_{DS} | Drain- Source Voltage | 55 | V |
| $I_D @ T_C = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 4.7 | A |
| $I_D @ T_C = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 3.8 | |
| I_{DM} | Pulsed Drain Current ① | 38 | |
| $P_D @ T_C = 25^\circ C$ | Power Dissipation | 2.0 | W |
| $P_D @ T_C = 70^\circ C$ | Power Dissipation | 1.3 | |
| | Linear Derating Factor | 0.016 | W/°C |
| V_{GS} | Gate-to-Source Voltage | ± 20 | V |
| V_{GSM} | Gate-to-Source Voltage Single Pulse $t_p < 10\mu s$ | 30 | V |
| E_{AS} | Single Pulse Avalanche Energy② | 72 | |
| dv/dt | Peak Diode Recovery dv/dt ③ | 5.0 | V/ns |
| T_J, T_{STG} | Junction and Storage Temperature Range | -55 to + 150 | °C |

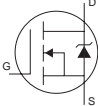
Thermal Resistance

| | Parameter | Typ. | Max. | Units |
|-----------------|------------------------------|------|------|-------|
| $R_{\theta JA}$ | Maximum Junction-to-Ambient⑤ | — | 62.5 | °C/W |

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------|--------------------------------------|------|-------|-------|---------------------|--|
| $V_{(BR)DSS}$ | Drain-to-Source Breakdown Voltage | 55 | — | — | V | $V_{GS} = 0V, I_D = 250\mu A$ |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient | — | 0.059 | — | V/ $^\circ\text{C}$ | Reference to 25°C , $I_D = 1\text{mA}$ |
| $R_{DS(on)}$ | Static Drain-to-Source On-Resistance | — | 0.043 | 0.050 | Ω | $V_{GS} = 10V, I_D = 4.7A$ ④ |
| | | — | 0.056 | 0.065 | | $V_{GS} = 4.5V, I_D = 3.8A$ ④ |
| $V_{GS(th)}$ | Gate Threshold Voltage | 1.0 | — | — | V | $V_{DS} = V_{GS}, I_D = 250\mu A$ |
| g_{fs} | Forward Transconductance | 7.9 | — | — | S | $V_{DS} = 10V, I_D = 4.5A$ |
| I_{DSS} | Drain-to-Source Leakage Current | — | — | 2.0 | μA | $V_{DS} = 55V, V_{GS} = 0V$ |
| | | — | — | 25 | | $V_{DS} = 55V, V_{GS} = 0V, T_J = 55^\circ\text{C}$ |
| I_{GSS} | Gate-to-Source Forward Leakage | — | — | -100 | nA | $V_{GS} = -20V$ |
| | Gate-to-Source Reverse Leakage | — | — | 100 | | $V_{GS} = 20V$ |
| Q_g | Total Gate Charge | — | 24 | 36 | nC | $I_D = 4.5A$ |
| Q_{gs} | Gate-to-Source Charge | — | 2.3 | 3.4 | | $V_{DS} = 44V$ |
| Q_{gd} | Gate-to-Drain ("Miller") Charge | — | 7.0 | 10 | | $V_{GS} = 10V$, See Fig. 10 ④ |
| $t_{d(on)}$ | Turn-On Delay Time | — | 8.3 | 12 | ns | $V_{DD} = 28V$ |
| t_r | Rise Time | — | 3.2 | 4.8 | | $I_D = 1.0A$ |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 32 | 48 | | $R_G = 6.0\Omega$ |
| t_f | Fall Time | — | 13 | 20 | | $R_D = 16\Omega$, ④ |
| C_{iss} | Input Capacitance | — | 740 | — | pF | $V_{GS} = 0V$ |
| C_{oss} | Output Capacitance | — | 190 | — | | $V_{DS} = 25V$ |
| C_{rss} | Reverse Transfer Capacitance | — | 71 | — | | $f = 1.0\text{MHz}$, See Fig. 9 |

Source-Drain Ratings and Characteristics

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|----------|---|------|------|------|-------|--|
| I_S | Continuous Source Current (Body Diode) | — | — | 2.0 | A | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I_{SM} | Pulsed Source Current (Body Diode) ① | — | — | 38 | | |
| V_{SD} | Diode Forward Voltage | — | — | 1.2 | V | $T_J = 25^\circ\text{C}, I_S = 2.0A, V_{GS} = 0V$ ③ |
| t_{rr} | Reverse Recovery Time | — | 60 | 90 | ns | $T_J = 25^\circ\text{C}, I_F = 2.0A$ |
| Q_{rr} | Reverse Recovery Charge | — | 120 | 170 | nC | $di/dt = -100A/\mu s$ ③ |

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting $T_J = 25^\circ\text{C}$, $L = 6.5\text{mH}$
 $R_G = 25\Omega, I_{AS} = 4.7A$. (See Figure 8)
- ③ $I_{SD} \leq 4.7A, di/dt \leq 220A/\mu s, V_{DD} \leq V_{(BR)DSS}, T_J \leq 150^\circ\text{C}$
- ④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
- ⑤ When mounted on 1 inch square copper board, $t < 10$ sec

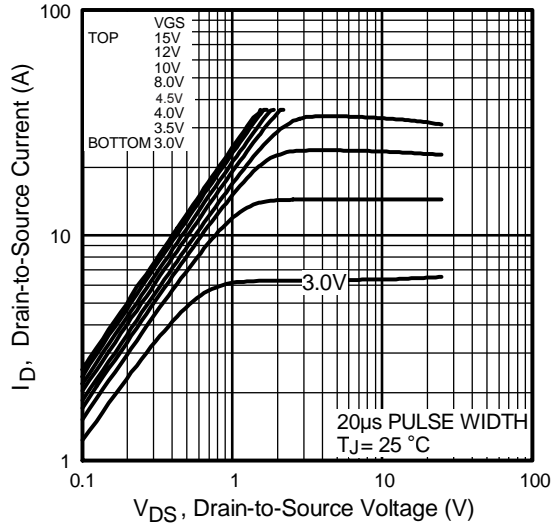


Fig 1. Typical Output Characteristics

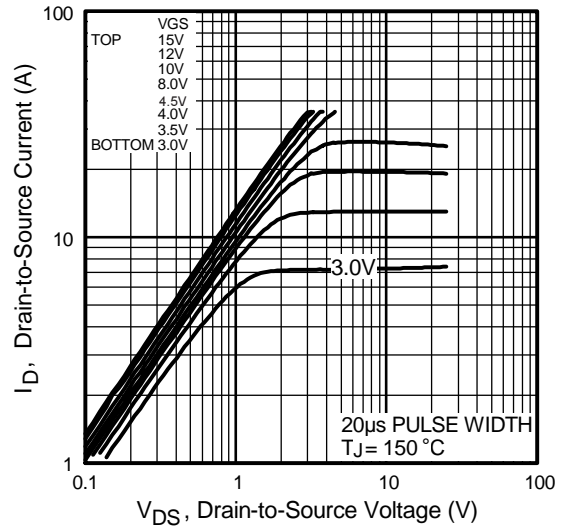


Fig 2. Typical Output Characteristics

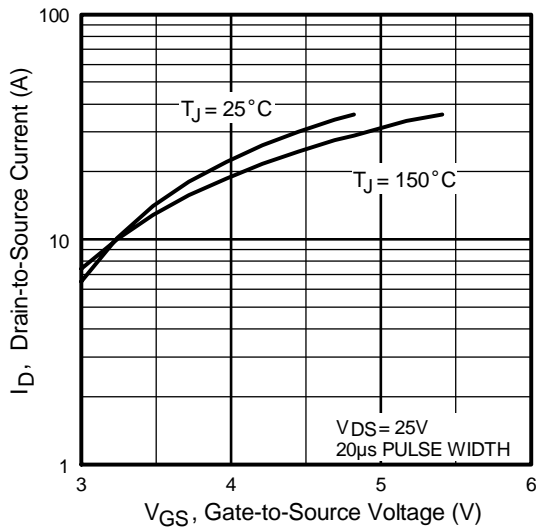


Fig 3. Typical Transfer Characteristics

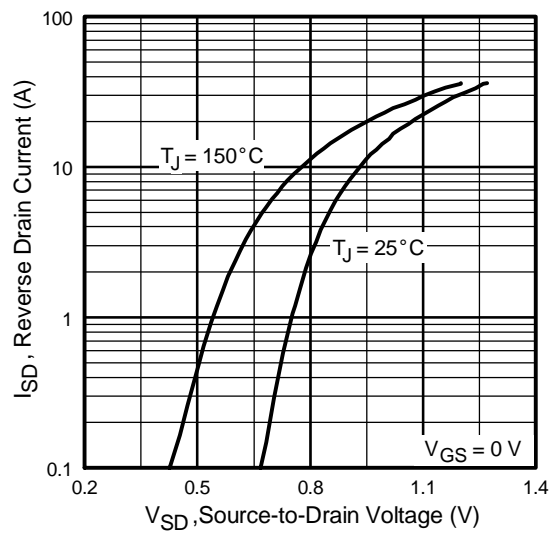


Fig 4. Typical Source-Drain Diode Forward Voltage

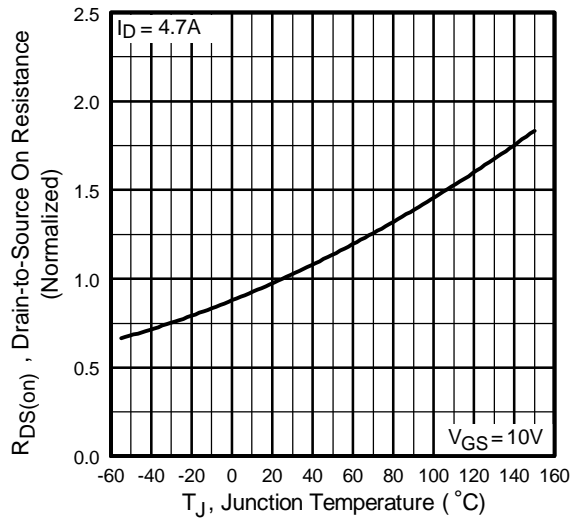


Fig 5. Normalized On-Resistance Vs. Temperature

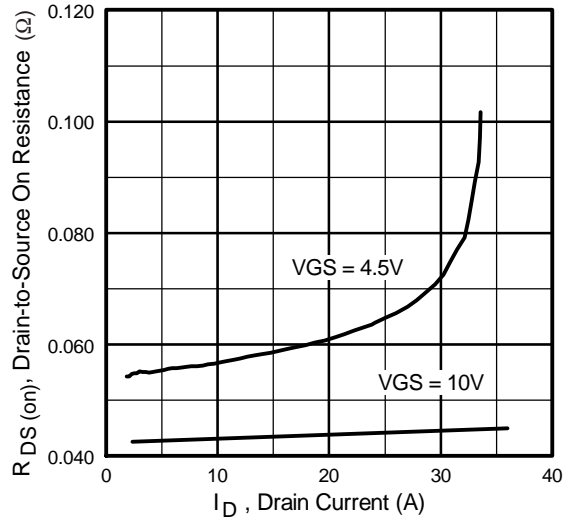


Fig 6. Typical On-Resistance Vs. Drain Current

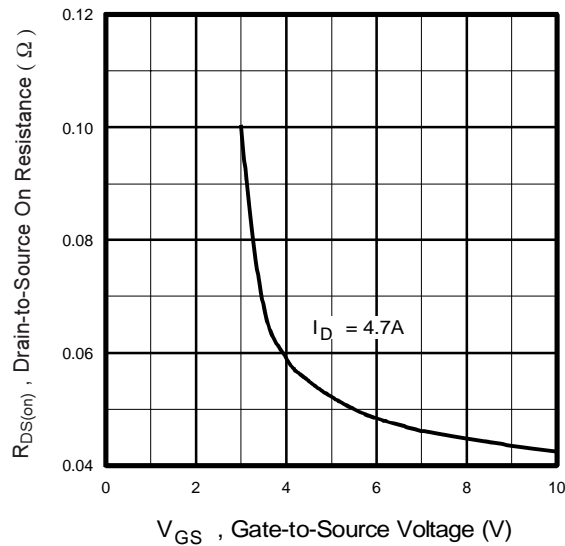


Fig 7. Typical On-Resistance Vs. Gate Voltage

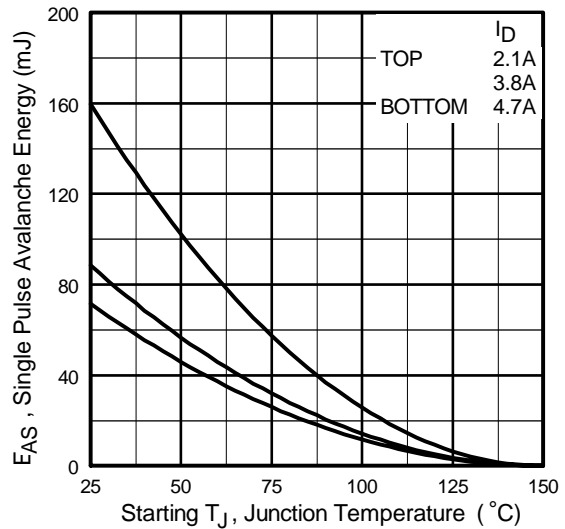


Fig 8. Maximum Avalanche Energy Vs. Drain Current

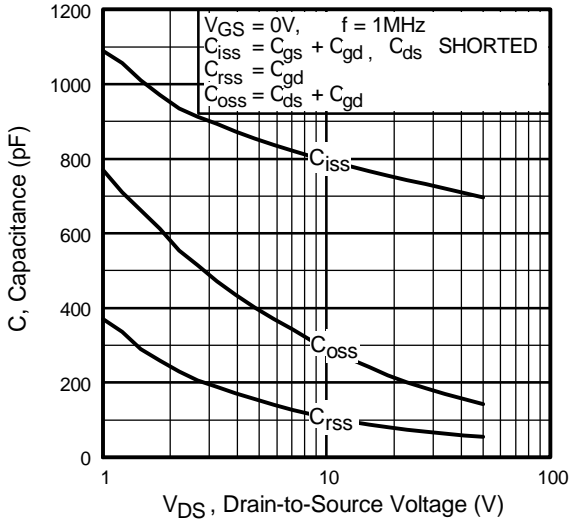


Fig 9. Typical Capacitance Vs. Drain-to-Source Voltage

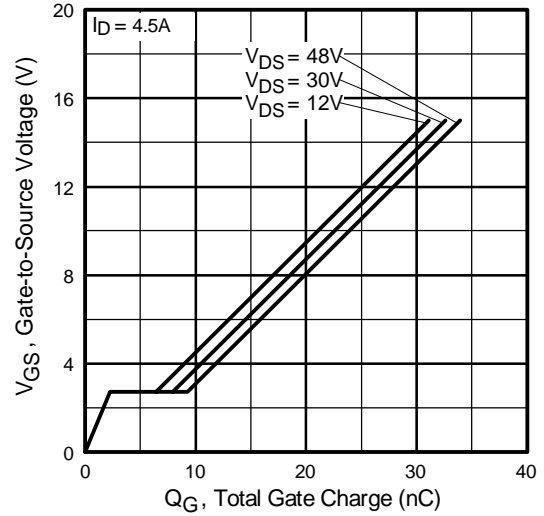


Fig 10. Typical Gate Charge Vs. Gate-to-Source Voltage

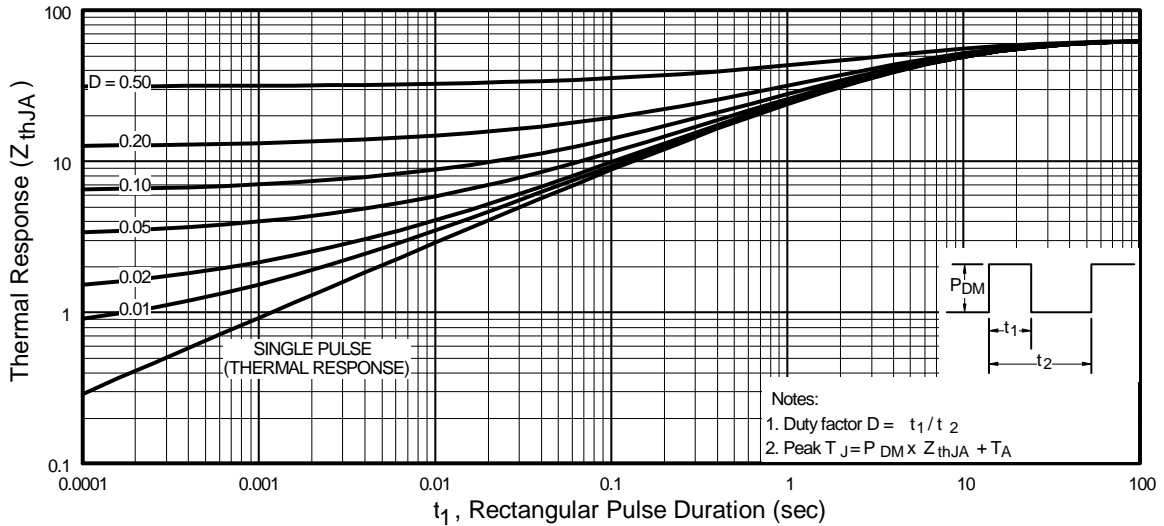
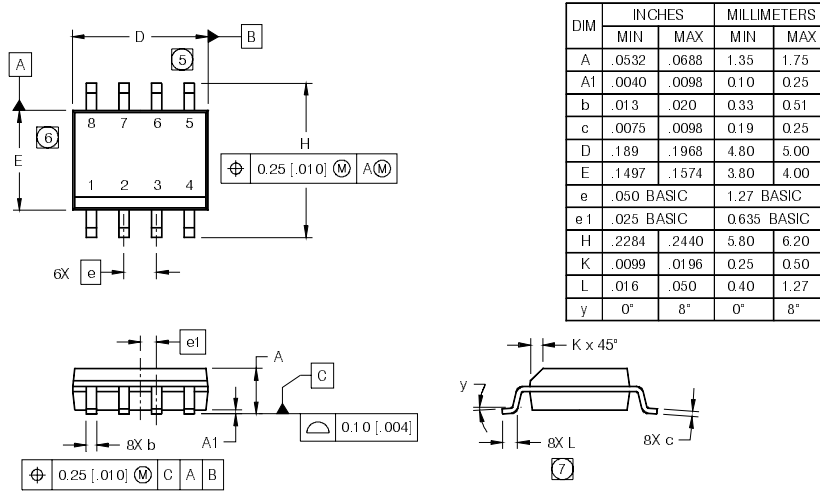


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

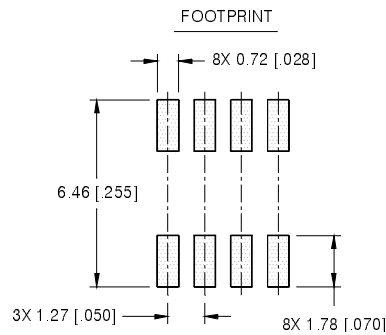
IRF7341IPbF

SO-8 Package Outline

Dimensions are shown in millimeters (inches)

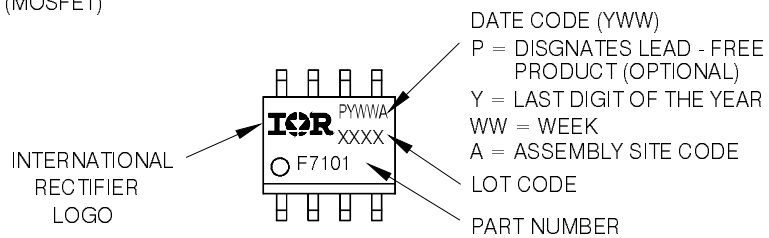


- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
 2. CONTROLLING DIMENSION: MILLIMETER
 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
 5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [0.006].
 6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [0.010].
 7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.



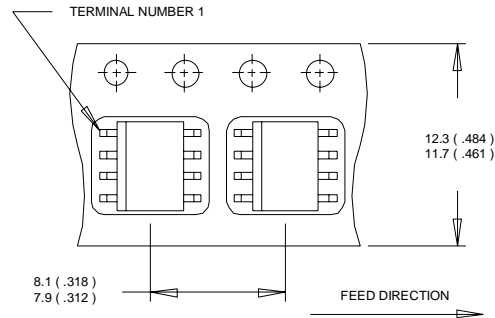
SO-8 Part Marking Information

EXAMPLE: THIS IS AN IRF7101 (MOSFET)

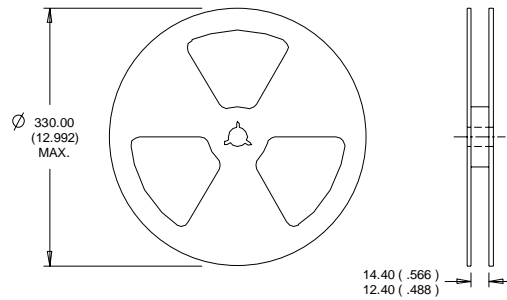


SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.
 This product has been designed and qualified for the Industrial market.
 Qualifications Standards can be found on IR's Web site.

International
IR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
 TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information. 07/2006